

Specification Sheet

P/N: MCM-9070M-SERIES-RU

Products: Certifications:

Molded Power Chokes ISO9001

Multilayer Chip Inductors IATF16949

<u>Lan Transformer</u> ISO14001

RF Passive / Antennas QC080000

Automotive

US Office Contact Us

5406 Bolsa Ave., Huntington Beach, CA 92649 (714) 898-8377 www.maglayersusa.com info@maglayersusa.com

T. SCOPE:

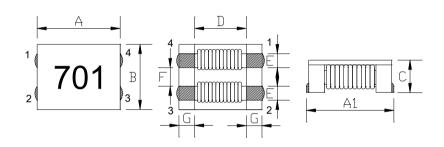
This specification applies to the Pb Free high current type SMD Common mode filter for MCM-9070M-SERIES

PRODUCT INDENTIFICATION

MCM - 9070M - Series-RU

- (1)
- 2
- (3)
- **1** Product Code
- **② Dimensions Code**
- **3 Impedance Code**

(1) SHAPES AND DIMENSIONS



A: 9.0±0.5 mm A1: 9.5±0.5 mm B: 7.0±0.5 mm C: 4.8Max. mm D: 5.6Typ. mm E: 1.5±0.2 mm F: 2.0±0.2 mm G: 1.7±0.2 mm

(2) ELECTRICAL SPECIFICATIONS

SEE TABLE 1

TEST INSTRUMENTS

Z : HP 4291B IMPEDANCE ANALYZER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

I.R: CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range -40° C \sim +125 $^{\circ}$ C (Including self temp. rise)

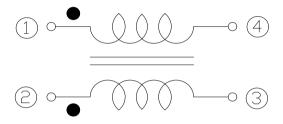
(3)-2 Storage temperature range -40° C \sim $+125^{\circ}$ C



TABLE 1

MAGLAYERS PT/NO.	Impedance(Ω) at 100MHz		Resistance RDC(Ω) Max.	Rated Current	Insulation Resistance	Rated Voltage
	Min.	Тур.	(1 line)	(A) Max.	(MΩ) Min.	(V)Max.
MCM-9070M-301-RU	225	300	6m	6.0	10	80
MCM-9070M-501-RU	450	600	8m	5.5	10	80
MCM-9070M-701-RU	500	700	10m	5.0	10	80
MCM-9070M-102-RU	750	1000	13m	4.0	10	80
MCM-9070M-222-RU	1700	2200	60m	2.5	10	80
MCM-9070M-272-RU	2000	2700	86m	2.0	10	80

CHARACTERISTICS(REFERENCE)



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS		
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .		
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.		
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering		
Soldering heat		© 300− soldering		
(reflow soldering)		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric eric conditions for 1 hour, after which the measurement shall be made.		
Terminal strength	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate , and then laterally apply a load 9.8N in the arrow direction.		
Strength on PC board bending	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate and then apply a load. Test board:FR4 100×40×1mm Fall speed:1mm/sec. Dimensions in mm		
High	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit		
temperature				
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.		
	The terminal electrode and the ferrite must not	Temperature: +125±2°C		
	damaged.	Applied voltage : Rated voltage		
		Applied current : Rated current Testing time : 500±12 hours		



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60±2℃ , Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value.	1 cycle
	Insulation resistance and DC resistance on the	30 min.
	specification(refer to clause 2-1) shall be met.	+125°C 30 sed
	The terminal electrode and the ferrite must	\ '/ \
	not damaged.	-40°C -\/ \/
		30 min. Testing time:100 cycle
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
	Insulation resistance and DC resistance on	board,the test shall be done.
	the specification(refer to clause 2-1)	Frequency : 10 to 55 Hz
	shall be met.	Amplitude : 1.52 mm
	The terminal electrode and the ferrite must	Dimension and times : X ,Y and Z directions
	not damaged.	for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated
		over the whole of the sample before hard, the sample shall
		then be preheated for about 2 minutes in a temperature
		of 130~150℃ and after it has been immersed to a depth
		0.5mm below for 3±0.2 seconds fully in molten solder
		M705 with a temperature of 245±5°C. More than 75% of the
		electrode sections shall be couered
		with new solder smoothly when the sample is taken out
		of the solder bath.

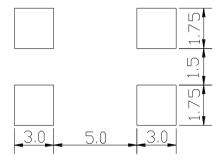


(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

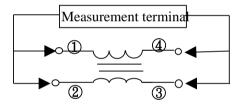
(STANDARD PATTERN) Unit:mm



(6) TEST EQUIPMENT

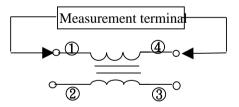
(6)-1 Impedance

Measured by using HP4291B RF Impedance Analyzer.



(6)-2 DC Resistance

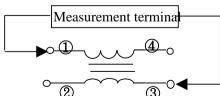
Measured by using Chroma 16502 milliohm meter.



(6)-3 Insulation Resistance

Measured by using Chroma 19073

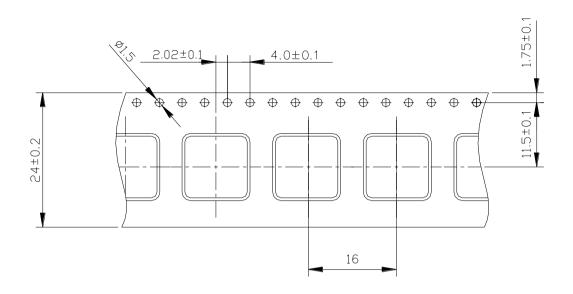
Measurement voltage: 50v, Measurement time: 60 sec.



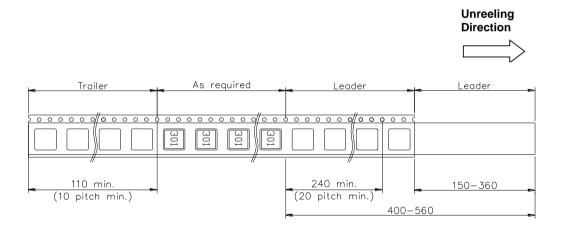


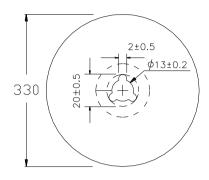
(6) PACKAGING

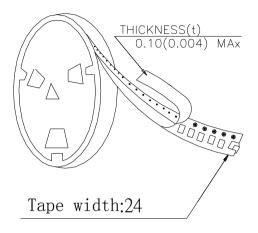
(6)-1 CARRIER TAPE DIMENSIONS (mm)



(6)-2 TAPING DIMENSIONS (mm)







(6)-4 QUANTITY

700pcs/Reel

The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.



TYPICAL ELECTRICAL CHARACTERISTICS

